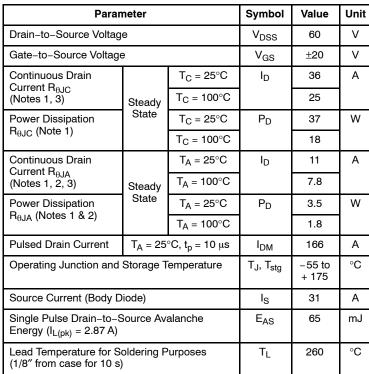
Power MOSFET 60 V, 15.0 mΩ, 36 A, Single N–Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- NVMFS5C677NLWF Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)



Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	4.1	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	43	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

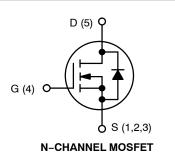
Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

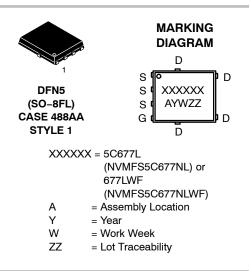


ON Semiconductor®

www.onsemi.com

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
60 V	15.0 m Ω @ 10 V	36 A
00 V	21.5 m Ω @ 4.5 V	30 A





ORDERING INFORMATION

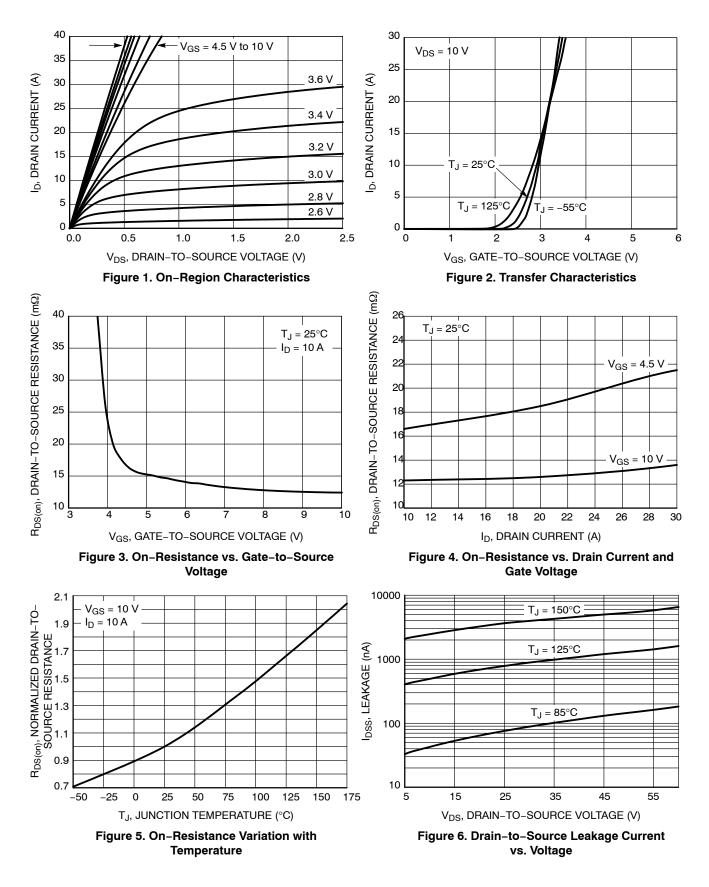
See detailed ordering, marking and shipping information on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = $25^{\circ}C$ unless otherwise specified)

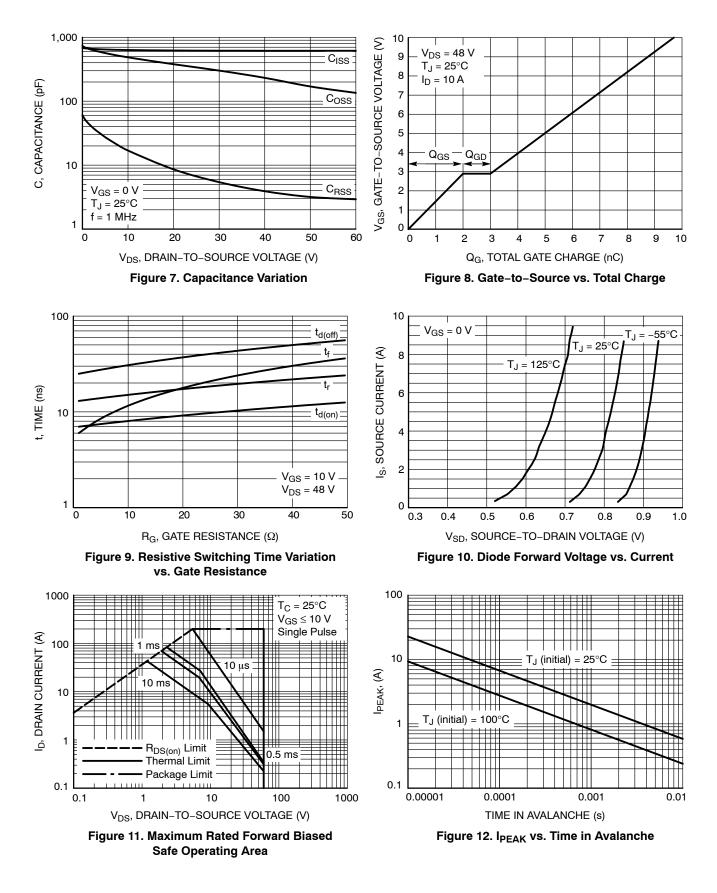
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Parameter	Symbol	Test Condi	tion	Min	Тур	Max	Unit	
$ \begin{array}{ c c c c c c } \hline Drain-to-Source Breakdown Voltage T_J & V_{(BFI)DSS}' \\ T_J & I_{DSS} & V_{DS} = 0 V, \\ V_{DS} = 60 V, \\ V_{DS} = 0 V, \\ V_{DS} = 0$	OFF CHARACTERISTICS					1		1	
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA		60			V	
$\begin{tabular}{ c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$		V _{(BR)DSS} / T _J				26		mV/°C	
$ \begin{array}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25 °C			10		
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			V _{DS} = 60 V	T _J = 125°C			250	μA	
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS}	₆ = 20 V			100	nA	
$\begin{array}{ c c c c c } \hline \begin{tabular}{ c c c c } \hline \begin{tabular}{ c c c c c } \hline \begin{tabular}{ c c c c c } \hline \begin{tabular}{ c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c } \hline \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	ON CHARACTERISTICS (Note 4)					1		1	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 25 μA		1.2		2.0	V	
$ \begin{array}{ c c c c } \hline V_{GS} = 4.5 \ V & b = 10 \ A & 17.9 & 21.5 \\ \hline V_{GS} = 4.5 \ V & b = 15 \ A & 27.5 & S \\ \hline \hline Provemond Transconductance & g_{FS} & $V_{DS} = 15 \ V, $l_{D} = 15 \ A & 27.5 & S \\ \hline \hline CHARGES AND CAPACITANCES & $V_{GS} = 0 \ V, $f = 1 \ MHz, $V_{DS} = 25 \ V & 340 & P \\ \hline \hline Output Capacitance & C_{RSS} & $V_{GS} = 0 \ V, $f = 1 \ MHz, $V_{DS} = 25 \ V & 340 & P \\ \hline \hline Total Gate Charge & $Q_{G(TOT)}$ & $V_{GS} = 45 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A & 4.5 & 0 \\ \hline Total Gate Charge & $Q_{G(TOT)}$ & $V_{GS} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A & 9.7 & 0 \\ \hline \hline Total Gate Charge & $Q_{G(TH)}$ & $V_{GS} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A & 9.7 & 0 \\ \hline \hline Threshold Gate Charge & Q_{GD} & $V_{GS} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A & 9.7 & 0 \\ \hline \hline 1 & 0 \\ \hline \hline Plateau \ Voltage & V_{GP} & $V_{GS} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A & 1 & 0 \\ \hline \hline 1 & 0 \\ \hline \hline Plateau \ Voltage & V_{GP} & $V_{GS} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A & 7 & 0 \\ \hline \hline 1 & 0 \\ \hline \hline Plateau \ Voltage & V_{GP} & $V_{GS} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A & $G = 1 \ \Omega & $V_{GS} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A \ R_{G} = 1 \ \Omega & $113 \ 10 \ 113 \ 0 \\ \hline \hline \hline Provemond Plateau \ Voltage & V_{GP} & $V_{GS} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A \ R_{G} = 1 \ \Omega & $0 \ Provemond Plateau \ Voltage & $V_{GS} = 0 \ V, $l_{S} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A \ R_{G} = 1 \ \Omega & $V_{GS} = 0 \ V, $l_{S} = 10 \ V, $V_{DS} = 48 \ V; $l_{D} = 10 \ A \ R_{G} = 1 \ \Omega & $V_{GS} = 0 \ V, $l_{S} = 10 \ V, l_{S}	Threshold Temperature Coefficient					-5.0		mV/°C	
$ \begin{array}{ c c c c c } \hline V_{GS} = 4.5 \ V & _{D} = 10 \ A & 17.9 & 21.5 \\ \hline \end{tabular} \begin{tabular}{ c c c c c } \hline \end{tabular} \\ \hline \end{tabular} \begin{tabular}{ c c c c c c } \hline \end{tabular} \begin{tabular}{ c c c c c c } \hline \end{tabular} \begin{tabular}{ c c c c c c } \hline \end{tabular} \begin{tabular}{ c c c c c c } \hline \end{tabular} \begin{tabular}{ c c c c c } \hline \end{tabular} \begin{tabular}{ c c c c c c c } \hline \end{tabular} \begin{tabular}{ c c c c c c c } \hline \end{tabular} \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 10 A		12.5	15.0		
			V _{GS} = 4.5 V	I _D = 10 A		17.9	21.5	mΩ	
$ \begin{array}{ c c c c c c } Input Capacitance & C_{ISS} \\ \hline Output Capacitance & C_{OSS} \\ \hline Output Capacitance & C_{RSS} \\ \hline V_{GS} = 0 \ V, \ f = 1 \ MHz, \ V_{DS} = 25 \ V \\ \hline Meverse Transfer Capacitance & C_{RSS} \\ \hline T \\ \hline Total Gate Charge & Q_{G(TOT)} \\ \hline Total Gate Charge & Q_{G(TOT)} \\ \hline Total Gate Charge & Q_{G(TOT)} \\ \hline Catal $	Forward Transconductance	9 _{FS}	V _{DS} =15 V, I _D	= 15 A		27.5		S	
$ \begin{array}{ c c c c c c c } \hline Output Capacitance & C_{OSS} & V_{GS} = 0 \ V, \ f = 1 \ MHz, \ V_{DS} = 25 \ V & 340 & P \\ \hline & 7 & 0 & P \\ \hline & 1 & 1 $	CHARGES AND CAPACITANCES					1		1	
$\begin{array}{ c c c c c c c } \hline Performant Product Prod$	Input Capacitance	C _{ISS}				620		pF	
$\begin{array}{ c c c c c } \hline Total Gate Charge & Q_G(TOT) & V_{GS} = 4.5 & V, V_{DS} = 48 & V; I_D = 10 & A & 4.5 & nC \\ \hline Total Gate Charge & Q_G(TOT) & V_{GS} = 10 & V, V_{DS} = 48 & V; I_D = 10 & A & 9.7 & nC \\ \hline Threshold Gate Charge & Q_G(TH) & & & & & & & & & & & & & & & & & & &$	Output Capacitance	C _{OSS}				340			
$ \begin{array}{ c c c c } \hline V_{GS} = 10 \ V, \ V_{DS} = 48 \ V; \ I_D = 10 \ A \\ \hline P \ A \\ \hline P \ A \\ \hline A \\$	Reverse Transfer Capacitance	C _{RSS}				7			
$ \begin{array}{ c c c c c } \hline Total Gate Charge & Q_G(TOT) & V_{GS} = 10 \ V, \ V_{DS} = 48 \ V; \ I_D = 10 \ A & 9.7 & nC \\ \hline \ Threshold Gate Charge & Q_G(TH) & \\ \hline \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	Total Gate Charge	Q _{G(TOT)}				4.5		nC	
$ \begin{array}{ c c c c c c c } \hline Gate-to-Source Charge & Q_{GS} \\ \hline Gate-to-Drain Charge & Q_{GD} \\ \hline Plateau Voltage & V_{GP} \\ \hline \\ \hline Plateau Voltage & V_{GP} \\ \hline \\ $	Total Gate Charge		V _{GS} = 10 V, V _{DS} = 48 V; I _D = 10 A			9.7		nC	
$ \begin{array}{ c c c c c c } \hline Gate-to-Drain Charge & Q_{GD} & V_{GS} = 10 \ V, \ V_{DS} = 48 \ V; \ I_D = 10 \ A & 1 & 1 & 1 & 1 & 1 & 1 & 1 & 1 & 1 &$	Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V, V _{DS} = 48 V; I _D = 10 A			1.3		nC	
$ \begin{array}{c c c c c c c c } \hline Gate-to-Drain Charge & Q_{GD} & & & & & & & & & & & & & & & & & & &$	Gate-to-Source Charge					2.1			
$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	Gate-to-Drain Charge	Q _{GD}				1			
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	Plateau Voltage	V _{GP}				3.0		V	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	SWITCHING CHARACTERISTICS (Note 5	5)							
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Turn–On Delay Time	t _{d(ON)}	V_{GS} = 10 V, V_{DS} = 48 V, I_{D} = 10 A, R_{G} = 1 Ω			7			
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Rise Time					13		- ns	
$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	Turn-Off Delay Time	t _{d(OFF)}				25			
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Fall Time					6			
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	DRAIN-SOURCE DIODE CHARACTERIS	STICS							
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Forward Diode Voltage	V _{SD}	$V_{CS} = 0 V_{CS}$	$T_J = 25^{\circ}C$		0.85	1.2		
Charge Time t _a V _{GS} = 0 V, dls/dt = 100 A/μs, 11.9 ns Discharge Time t _b I<		$I_{\rm S} = 10 \rm A$	T _J = 125°C		0.72		V		
Discharge Time t_b $l_S = 10 \text{ A}$ 11.8	Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dls/dt = 100 A/µs,			23.8			
Discharge Time t_b $I_S = 10 \text{ A}$ 11.8	Charge Time	t _a				11.9		ns	
	Discharge Time					11.8			
	Reverse Recovery Charge					11.6		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300 \ \mu$ s, duty cycle $\leq 2\%$. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

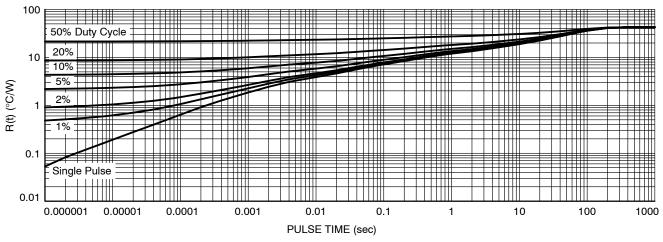


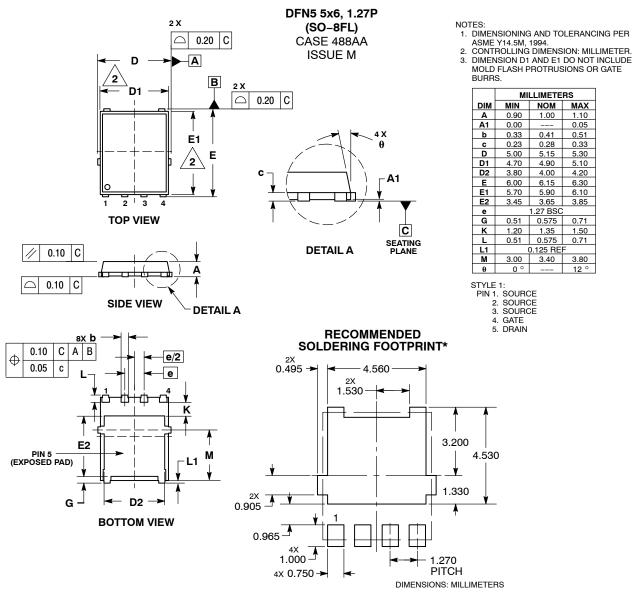
Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMFS5C677NLT1G	5C677L	DFN5 (Pb–Free)	1500 / Tape & Reel
NVMFS5C677NLWFT1G	677LWF	DFN5 (Pb-Free, Wettable Flanks)	1500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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